

# ICEP2010

International Conference on Electronics Packaging

Organizing Committee  
3-12-2 Nishiogikita, Suginami-ku, Tokyo 167-0042, Japan  
Tel: 81-3-5310-2011 Fax: 81-3-5310-2011  
E-mail: icep2010@jiep.or.jp

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June 7, 2011

Dear Prof. Nogita,

Paper Title: Trace Element Distribution in Solder Joints between Sn-based Solders and Cu Substrates

Paper ID: FB1-4

Authors: K. Nogita, H. Yasuda, C. M. Gourlay, S. Suenaga, H. Tsukamoto, S. D. McDonald, A. Takeuchi, K. Uesugi, The University of Queensland, Osaka University Imperial College, Nihon Superior, Japan Synchrotron Radiation Research Institute / Australia, Japan, U.K.

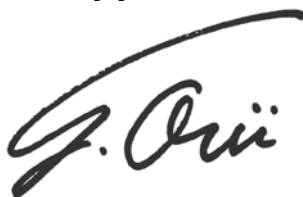
Paper Title: Lead-Free Solders for Electric Vehicles – Global Green Challenge Eco-Challenge Racing

Paper ID: FB2-1

Authors: K. Nogita, M. Greaves, B. Guymer, B. Walsh, J. Kennedy, M. Duke, T. Nishimura, The University of Queensland, Ultramotive Technologies, Tritium, The University of Waikato, Nihon Superior / Australia, New Zealand, Japan

On behalf of the Technical Program Committee of ICEP2010, we are pleased to inform you that after review by the Technical Program Committee of ICEP2010, the papers entitled above had been accepted for oral presentation and written publication at the International Conference on Electronic Packaging 2010 (ICEP 2010), which was held at Sapporo Convention Center, Hokkaido, Japan, from May 12 to 14, 2010.

Sincerely yours,



Mr. Yasumitsu Orii

General Chairperson of the Technical Program Committee of ICEP 2010